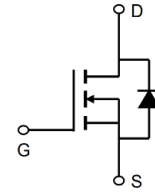


## 100V N-Channel Enhancement Mode MOSFET

### Description

The AP15N10P/T/F uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.



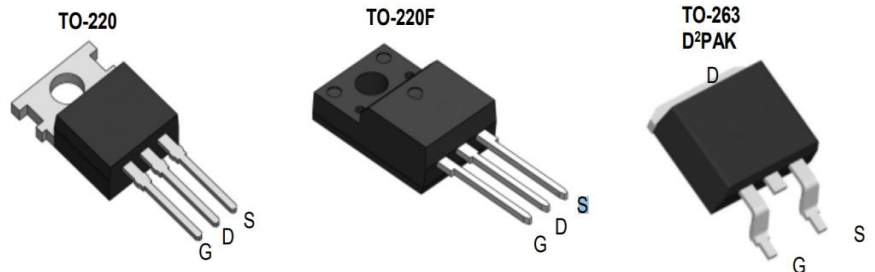
### General Features

$V_{DS} = 100V$   $I_D = 15A$

$R_{DS(ON)} < 100m\Omega @ V_{GS}=10V$  (Type: 72m $\Omega$ )

### Application

- Automotive lighting
- Load switch
- Uninterruptible power supply



### Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
AP15N10P	TO-220-3L	AP15N10P XXX YYYY	1000
AP15N10T	TO-263-3L	AP15N10T XXX YYYY	800
AP15N10F	TO-220F-3L	AP15N10F XXX YYYY	1000

### Absolute Maximum Ratings (TC=25°C unless otherwise noted)

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	100	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>C</sub> =25°C	Drain Current, V <sub>GS</sub> @ 10V	15	A
I <sub>D</sub> @T <sub>C</sub> =100°C	Drain Current, V <sub>GS</sub> @ 10V	7.5	A
IDM	Pulsed Drain Current <sup>1</sup>	45	A
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation	30	W
P <sub>D</sub> @T <sub>A</sub> =25°C	Total Power Dissipation <sup>3</sup>	2.7	W
TSTG	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C
R $\theta$ JA	Maximum Thermal Resistance, Junctionambient	62.5	°C/W
R $\theta$ JC	Maximum Thermal Resistance, Junction-case	5.1	°C/W



## 100V N-Channel Enhancement Mode MOSFET

### Electrical Characteristics@T<sub>j</sub>=25°C(unless otherwise specified)

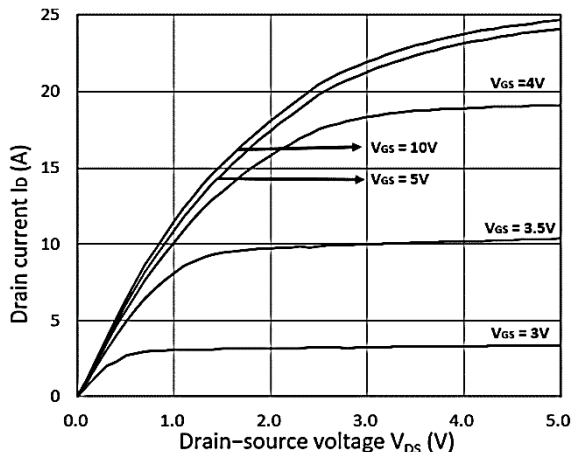
Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
V(BR)DSS	Drain-Source Breakdown Voltage	VGS=0V, ID=250μA	100	107	-	V
IDSS	Zero Gate Voltage Drain Current	VDS=100V, VGS=0V,	-	-	1.0	μA
IGSS	Gate to Body Leakage Current	VDS=0V, VGS=±20V	-	-	±100	nA
VGS(th)	Gate Threshold Voltage	VDS=VGS, ID=250μA	1.2	2.0	2.5	V
RDS(on)	Static Drain-Source on-Resistance note3	VGS=10V, ID=5A	-	72	100	mΩ
		VGS=4.5V, ID=3A	-	88	110	mΩ
g fs	Forward Transconductance	V DS =5V , I D =5A		14		S
RG	Gate Resistance	VDS = 0V, VGS = 0V,f =1MHz		3		Ω
Ciss	Input Capacitance	VDS=15V, VGS=0V, f=1.0MHz	-	1100	-	pF
Coss	Output Capacitance		-	55	-	pF
Crss	Reverse Transfer Capacitance		-	40	-	pF
Qg	Total Gate Charge	VDS=50V, ID=5A, VGS=10V	-	11.9	-	nC
Qgs	Gate-Source Charge		-	2.8	-	nC
Qgd	Gate-Drain("Miller") Charge		-	1.7	-	nC
td(on)	Turn-on Delay Time	VDS=30V, ID=5A, RG=1.8Ω, VGS=10V	-	3.8	-	ns
tr	Turn-on Rise Time		-	25.8	-	ns
td(off)	Turn-off Delay Time		-	16	-	ns
tf	Turn-off Fall Time		-	8.8	-	ns
IS	Continuous Source Current1,5	VG=VD=0V , Force Current	-	-	14.6	A
ISM	Pulsed Source Current2,5		-	-	25	A
VSD	Diode Forward Voltage2	VGS=0V, IS=10A	-	-	1.2	V

#### Note :

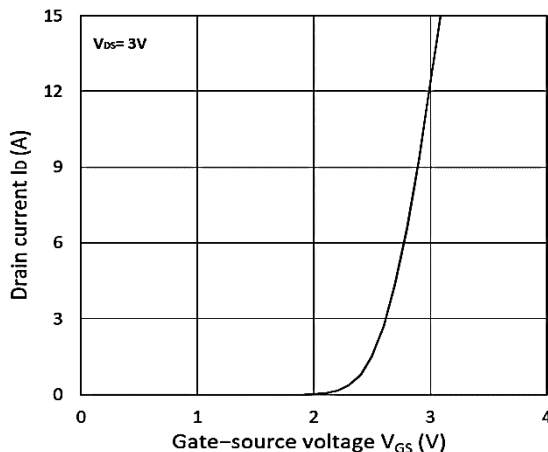
- 1、The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- 2、The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$
- 3、The power dissipation is limited by 150°C junction temperature
- 4、The data is theoretically the same as I D and I DM , in real applications , should be limited by total power dissipation.

**100V N-Channel Enhancement Mode MOSFET**

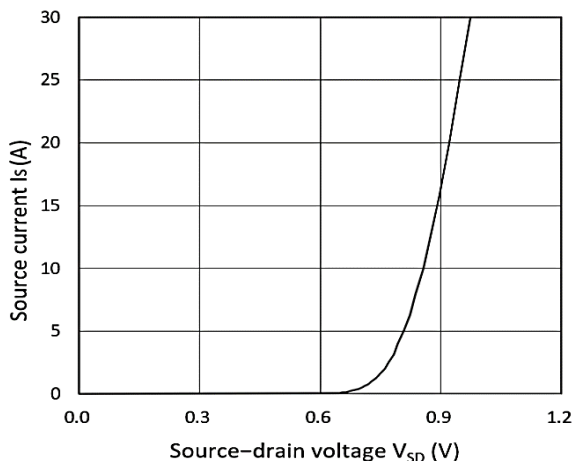
**Typical Characteristics**



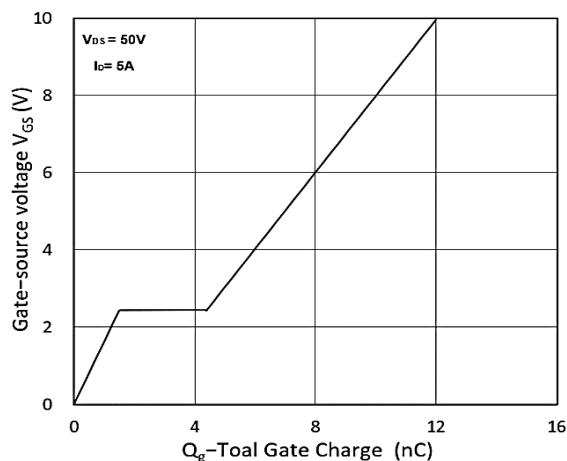
**Figure 1. Output Characteristics**



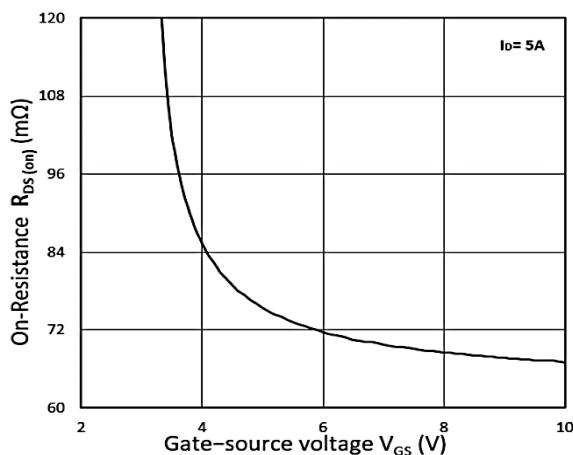
**Figure 2. Transfer Characteristics**



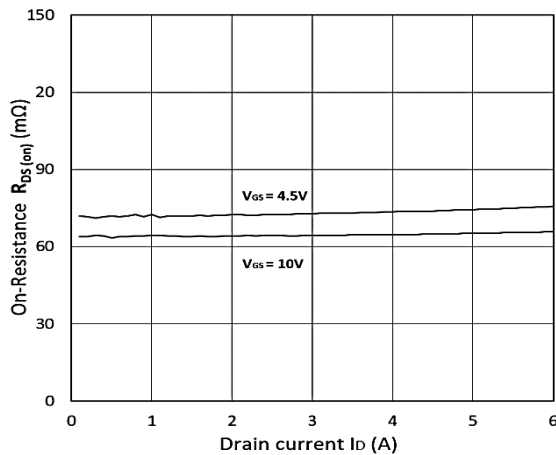
**Figure 3. Forward Characteristics of Reverse**



**Figure 4. Gate Charge Characteristics**



**Figure 5.  $R_{DS(on)}$  vs.  $V_{GS}$**



**Figure 6.  $R_{DS(on)}$  vs.  $I_D$**

**100V N-Channel Enhancement Mode MOSFET**

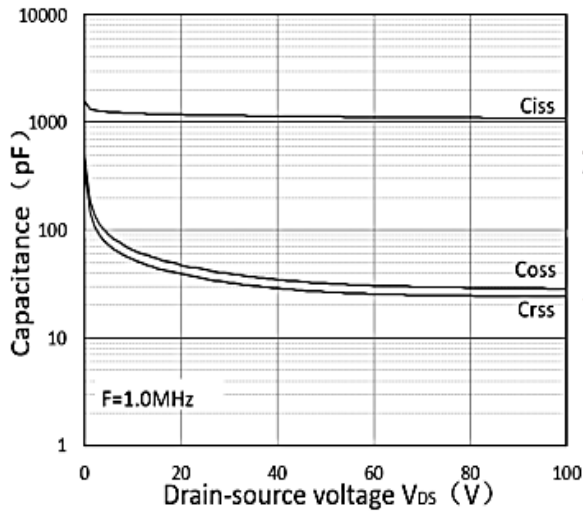


Figure 7. Capacitance Characteristics

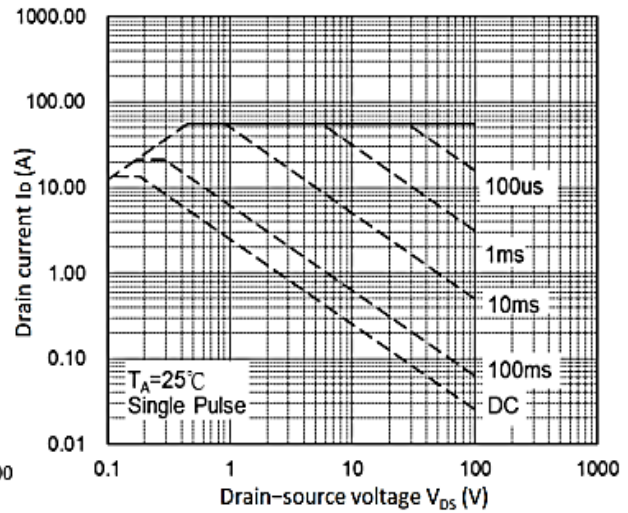


Figure 8. Safe Operating Area

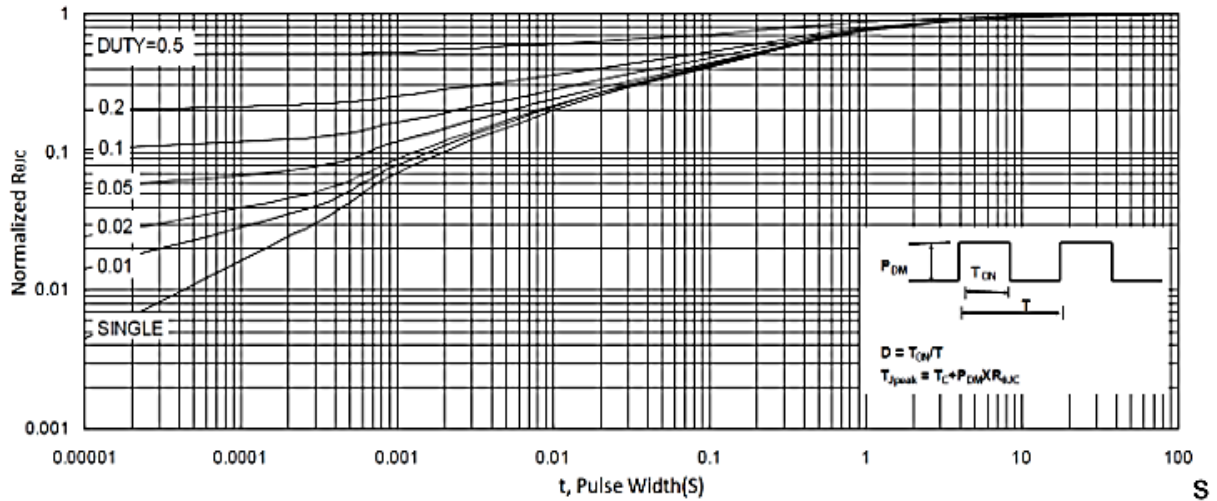


Figure 9. Normalized Maximum Transient Thermal Impedance

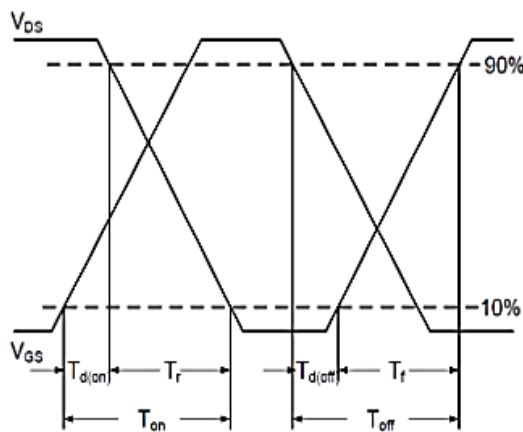


Figure 10. Switching Time Waveform

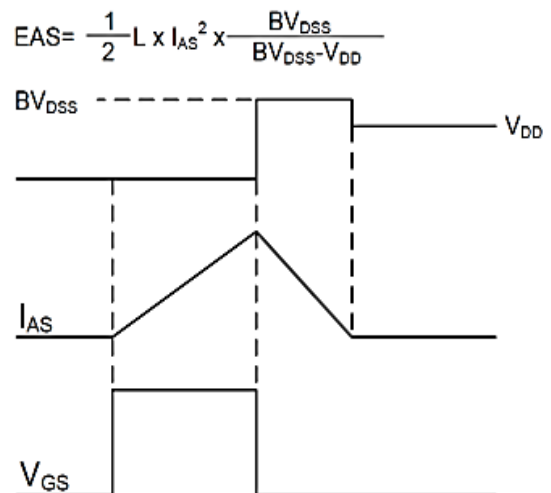


Figure 11. Unclamped Inductive Switching Waveform



## 100V N-Channel Enhancement Mode MOSFET

### Package Mechanical Data-TO-X

